



Docket No.: M4065.0468/P468
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Phillip E. Byrd, et al.

Application No.: 09/941,761

Allowed: May 20, 2003

Filed: August 30, 2001

Group Art Unit: 2812

For: STRUCTURE FOR TEMPORARILY
ISOLATING A DIE FROM A
COMMON CONDUCTOR TO
FACILITATE WAFER LEVEL
TESTING (AS AMENDED HEREIN)

Examiner: A. Stevenson

AMENDMENT UNDER 37 CFR § 1.312

Attn: Box Issue Fee
Commissioner for Patents
Washington, DC 20231

Dear Sir:

Prior to issuance, please amend the above-captioned application as follows:

Amendments to the Specification begin on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.